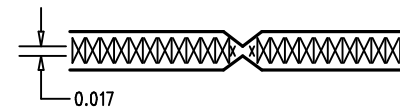


REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		

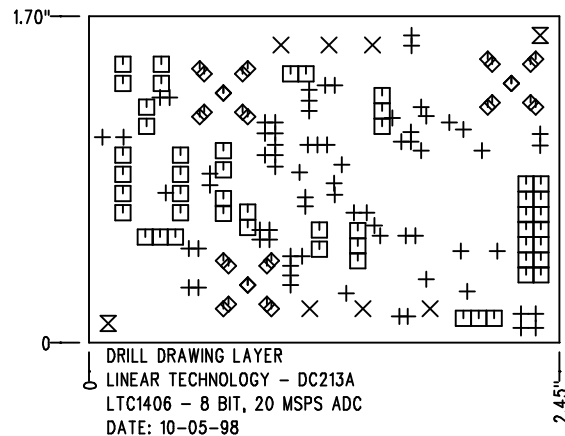
SIZE	QTY	SYM	PLTD
0.02	73	+	PLTD
0.094	6	×	PLTD
0.035	50	□	PLTD
0.055	30	◇	PLTD
0.07	2	⊗	NPLTD

NOTES : Unless Otherwise Specified


1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 2 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.



SHOWN FROM COMPONENT SIDE

APPROVALS			 LINEAR TECHNOLOGY 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
DRAWN	INIT	DATE		
CHECK			TITLE: Fabrication Drawing 8 BIT, 20 MSPS ADC	
DESIGN	KIM T.	10-05-98		
ENGR	KEVIN H.	10-05-98	SIZE A DEMO DC213A-LTC1406 REV. A	
SCALE = NONE			DES- 0000	SHT 1 of 1